

PATENT ABSTRACTS OF JAPAN

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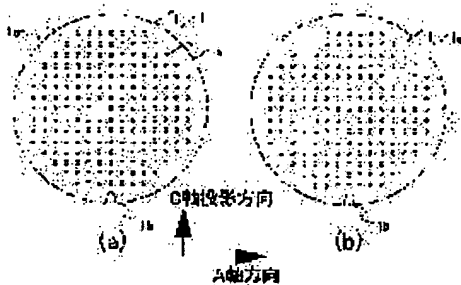
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(54) WAFER SUPPORT SUBSTRATE

(57)Abstract:

PROBLEM TO BE SOLVED: To solve a problem such that, when a back surface of a compound semiconductor wafer is processed in a semiconductor manufacturing process, if sapphire is used as a substrate for supporting the wafer, when aligning is performed, a birefringence is caused from optical anisotropy, so that the aligning precision is lowered.

SOLUTION: A main surface of a sapphire-made support substrate is set to be within R surface $\pm 2^\circ$, and a display part for displaying a C axis projection direction is provided.



LEGAL STATUS

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